

OPA2241 OPA2241 OPA4241 OPA251 OPA2251 OPA2251

Single-Supply, *Micro*POWER OPERATIONAL AMPLIFIERS

OPA241 Family optimized for +5V supply. **OPA251 Family** optimized for ±15V supply.

FEATURES

- *Micro*POWER: $I_Q = 25\mu A$
- SINGLE-SUPPLY OPERATION
- RAIL-TO-RAIL OUTPUT (within 50mV)
- WIDE SUPPLY RANGE Single Supply: +2.7V to +36V Dual Supply: ±1.35V to ±18V
- LOW OFFSET VOLTAGE: ±250µV max
- HIGH COMMON-MODE REJECTION: 124dB
- HIGH OPEN-LOOP GAIN: 128dB
- SINGLE, DUAL, AND QUAD

APPLICATIONS

- BATTERY OPERATED INSTRUMENTS
- PORTABLE DEVICES
- MEDICAL INSTRUMENTS
- TEST EQUIPMENT

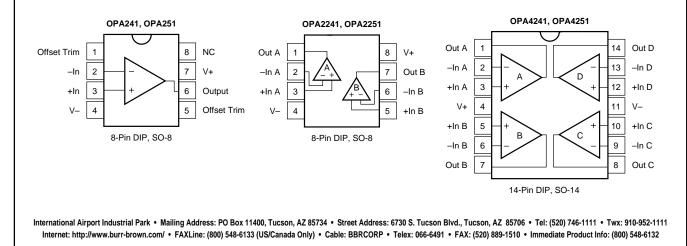
DESCRIPTION

The OPA241 series and OPA251 series are specifically designed for battery powered, portable applications. In addition to very low power consumption ($25\mu A$), these amplifiers feature low offset voltage, rail-to-rail output swing, high common-mode rejection, and high open-loop gain.

The OPA241 series is optimized for operation at low power supply voltage while the OPA251 series is optimized for high power supplies. Both can operate from either single (+2.7V to +36V) or dual supplies ($\pm 1.35V$ to $\pm 18V$). The input common-mode voltage range extends 200mV below the negative supply—ideal for single-supply applications.

They are unity-gain stable and can drive large capacitive loads. Special design considerations assure that these products are easy to use. High performance is maintained as the amplifiers swing to their specified limits. Because the initial offset voltage ($\pm 250\mu V$ max) is so low, user adjustment is usually not required. However, external trim pins are provided for special applications (single versions only).

The OPA241 and OPA251 (single versions) are available in standard 8-pin DIP and SO-8 surface-mount packages. The OPA2241 and OPA2251 (dual versions) come in 8-pin DIP and SO-8 surface-mount packages. The OPA4241 and OPA4251 (quad versions) are available in 14-pin DIP and SO-14 surface-mount packages. All are fully specified from -40° C to $+85^{\circ}$ C and operate from -55° C to $+125^{\circ}$ C.



SPECIFICATIONS: $V_s = 2.7V$ to 5V

At T_A = +25°C, R_L = 100k Ω connected to V_S/2, unless otherwise noted. **Boldface** limits apply over the specified temperature range, $T_A = -40^{\circ}C$ to $+85^{\circ}C$.

| | | OPA | 2241UA, | PA | OP | | | |
|---|---|--|--|--|---|---|---|---|
| | CONDITION | MIN | TYP ⁽¹⁾ | МАХ | MIN | TYP ⁽¹⁾ | МАХ | UNITS |
| V _{OS} dV _{OS} /dT PSRR | $T_{A} = -40^{\circ}C \text{ to } +85^{\circ}C$ $V_{S} = 2.7V \text{ to } 36V$ $V_{S} = 2.7V \text{ to } 36V$ | | ±50 ± 100 ± 0.4 3 0.3 | ±250 ± 400 30 30 30 | | ±100 ±130 ±0.6 * | * * | μV μV μV/°C μV/∨ μV/∨ μV/∨ |
| I _B I _{OS} | | | -4 ±0.1 | -20 -25 ±2 ±2 | | * | | nA nA nA nA |
| | | | 1 45 40 | | | * * * | | µVp-p nV/√Hz fA/√Hz |
| V _{CM} CMRR | $V_{CM} = -0.2V$ to (V+) -0.8V $V_{CM} = 0V$ to (V+) -0.8V | -0.2 80 80 | 106 | (V+) -0.8 | | * | | V dB dB |
| | | | 10 ⁷ 2 10 ⁹ 4 | | | * | | Ω pF Ω pF |
| A _{OL} | $R_L = 100k\Omega$, $V_0 = (V-)+100mV$ to $(V+)-100mV$ $R_L = 100k\Omega$, $V_0 = (V-)+100mV$ to $(V+)-100mV$ $R_L = 10k\Omega$, $V_0 = (V-)+200mV$ to $(V+)-200mV$ $R_L = 10k\Omega$, $V_0 = (V-)+200mV$ to $(V+)-200mV$ | 100 100 100 | 120 120 | | | * | | dB dB dB dB |
| GBW SR | $V_{S} = 5V, G = 1$ $V_{IN} \bullet G = V_{S}$ | 100 | 35 0.01 60 | | | * * * | | kHz V/μs μs |
| Vo | R_L = 100kΩ to V _S /2, $A_{OL} \ge$ 70dB R_L = 100kΩ to V _S /2, $A_{OL} \ge$ 100dB R_L = 100kΩ to V _S /2, $A_{OL} \ge$ 100dB R_L = 10kΩ to V ₂ /2, $A_{OL} \ge$ 100dB | | 50 75 | 100 100 200 | | * * | | mV mV mV mV |
| I _{SC} | $R_L = 10k\Omega$ to $V_S/2$, $A_{OL} \ge 100dB$ | See | -24/+4 -30/+4 | 200 | | * * | | mV mA mA |
| V _s I _Q | $T_{A} = -40^{\circ}C \text{ to } +85^{\circ}C$ $I_{O} = 0$ $I_{O} = 0$ | +2.7 | | | * | * | * | ν ν μΑ μΑ |
| $	heta_{JA}$ | | -40 -55 -55 | 100 150 80 | +85 +125 +125 | * * | * * | * * * | °C °C °C °C °C/W °C/W °C/W |
| | dV _{OS} /dT PSRR I _B I _{OS} V _{CM} CMRR A _{OL} A _{OL} GBW SR V _O I _{SC} C _{LOAD} V _S I _Q | $\begin{tabular}{ c c c c c } \hline V_{OS} \\ dV_{OS}/dT \\ PSRR \\ \hline T_A = -40^\circ C \ to +85^\circ C \\ V_S = 2.7V \ to \ 36V \\ \hline V_S = 2.7V \ to \ 36V \\ \hline V_S = 2.7V \ to \ 36V \\ \hline \\ $ | $\begin{tabular}{ c c c c } \hline $$ CONDITION$ & $$ MIN$ & $$ MIN$ & $$ MIN$ & $$ $$ $$ $$ $$ $$ $$ $$ $$ $$ $$ $$ $ | $\begin{array}{ c c c c c } \hline & & & & & & & & & & & & & & & & & & $ | $ \begin{array}{c c c c c c c c c c c c c c c c c c c $ | $\begin{array}{ c c c c c } \hline & \hline $ | $ \begin{array}{ c c c c c } \hline & OPA2241UA, PA & OPA2251UA, OPA2251UA, OPA2251UA, OPA2251UA, OPA251UA, OPA2$ | $\begin{array}{ c c c c c c } \hline & \hline $ |

* Specifications the same as OPA241UA, PA.

NOTES: (1) V_S = +5V. (2) The negative sign indicates input bias current flows out of the input terminals. (3) Output voltage swings are measured between the output and power supply rails.

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SPECIFICATIONS: $V_S = \pm 15V$

At $T_A = +25^{\circ}C$, $R_L = 100k\Omega$ connected to ground, unless otherwise noted. Boldface limits apply over the specified temperature range, $T_A = -40^{\circ}C$ to +85°C.

| | | | OP | A241UA, F A2241UA, A4241UA, | PA | OPA251UA, PA OPA2251UA, PA OPA4251UA, PA | | | |
|--|---|---|-------------|---|--------|--|--|--|---|
| PARAMETER | | CONDITION | MIN | ТҮР | МАХ | MIN | ТҮР | MAX | UNITS |
| OFFSET VOLTAGEInput Offset Voltage $T_A = -40^{\circ}C$ to $+85^{\circ}C$ vs Temperaturevs Power Supply $T_A = -40^{\circ}C$ to $+85^{\circ}C$ Channel Separation (dual, quad) | V _{OS} dV _{OS} /dT PSRR | T_A = −40°C to +85°C V _S = ±1.35V to ±18V V _S = ±1.35V to ±18V | | ±100 ± 150 ± 0.6 * | * * | | ±50 ±100 ±0.5 3 0.3 | ±250 ± 300 30 30 30 | μV μV μV/°C μV/V μV/V μV/V |
| INPUT BIAS CURRENT Input Bias Current ⁽¹⁾ $T_A = -40^{\circ}$ C to +85°C Input Offset Current $T_A = -40^{\circ}$ C to +85°C | I _B I _{OS} | | | * | | | -4 ±0.1 | -20 -25 ±2 ±2 | nA nA nA nA |
| NOISE Input Voltage Noise, f = 0.1Hz to 1 Input Voltage Noise Density, f = 1k Current Noise Density, f = 1kHz | | | | * * * | | | 1 45 40 | | μVp-p nV/√Hz fA/√Hz |
| INPUT VOLTAGE RANGE Common-Mode Voltage Range Common-Mode Rejection Ratio $T_A = -40^{\circ}$ C to +85°C | V _{CM} CMRR | $V_{CM} = -15.2V$ to 14.2V $V_{CM} = -15V$ to 14.2V | | * | | (V–) –0.2 100 100 | 124 | (V+) -0.8 | V dB dB |
| INPUT IMPEDANCE Differential Common-Mode | | | | * | | | 10 ⁷ 2 10 ⁹ 4 | | Ω pF Ω pF |
| OPEN-LOOP GAIN Open-Loop Voltage Gain $T_A = -40^{\circ}C$ to +85°C $T_A = -40^{\circ}C$ to +85°C | A _{OL} | | | * | | 100 100 100 100 | 128 128 | | dB dB dB dB |
| FREQUENCY RESPONSE Gain-Bandwidth Product Slew Rate Overload Recovery Time | GBW SR | $G = 1$ $V_{IN} \bullet G = V_{S}$ | | * * * | | | 35 0.01 60 | | kHz V/μs μs |
| OUTPUT Voltage Output Swing from Rail ⁽²⁾ $T_A = -40^{\circ}C \text{ to } +85^{\circ}C$ | Vo | $\begin{array}{l} R_L = 100 k\Omega, \ A_{OL} \geq 70 dB \\ R_L = 100 k\Omega, \ A_{OL} \geq 100 dB \\ R_L = 100 k\Omega, \ A_{OL} \geq 100 dB \\ R_L = 20 k\Omega, \ A_{OL} \geq 100 dB \end{array}$ | | * * | | | 50 75 100 | 250 250 300 | mV mV mV mV |
| $T_A = -40^{\circ}C$ to +85°C Short-Circuit Current Single Versions Dual Versions Capacitive Load Drive | I _{SC} C _{LOAD} | $R_{L} = 20k\Omega, \ A_{OL} \ge 100dB$ $R_{L} = 20k\Omega, \ A_{OL} \ge 100dB$ | | * * | | See | -21/+4 -50/+4 Typical C | 300 | mV mA mA |
| POWER SUPPLY Specified Voltage Range Operating Voltage Range Quiescent Current (per amplifier) $T_A = -40^{\circ}$ C to +85°C | V _s I _Q | $T_{A} = -40^{\circ}C \text{ to } +85^{\circ}C$ $I_{O} = 0$ $I_{O} = 0$ | * | * | * | ±1.35 | ±15 ±27 | ±18 ±38 ±45 | V V μΑ μΑ |
| TEMPERATURE RANGE Specified Range Operating Range Storage Range Thermal Resistance | $	heta_{JA}$ | | * * * | | * * * | -40 -55 -55 | | +85 +125 +125 | °℃ ℃ ℃ |
| 8-Pin DIP SO-8 Surface Mount 14-Pin DIP SO-14 Surface Mount | | | | * * * | | | 100 150 80 100 | | °C/W °C/W °C/W °C/W |

 $\boldsymbol{\ast}$ Specifications the same as OPA251UA, PA.

NOTES: (1) The negative sign indicates input bias current flows out of the input terminals. (2) Output voltage swings are measured between the output and power supply rails.



ABSOLUTE MAXIMUM RATINGS⁽¹⁾

| Supply Voltage, V+ to V | |
|---|--------------------------|
| Input Voltage ⁽²⁾ | (V–) –0.5V to (V+) +0.5V |
| Output Short Circuit to Ground ⁽³⁾ | Continuous |
| Operating Temperature | –55°C to +125°C |
| Storage Temperature | –55°C to +125°C |
| Junction Temperature | 150°C |
| Lead Temperature (soldering, 10s) | 300°C |

NOTES: (1) Stresses above these ratings may cause permanent damage. (2) Input terminals are diode-clamped to the power supply rails. Input signals that can swing more that 0.5V beyond the supply rails should be current-limited to 5mA or less. (3) One amplifier per package.



This integrated circuit can be damaged by ESD. Burr-Brown recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE/ORDERING INFORMATION

| PRODUCT | SPECIFIED VOLTAGE | OPERATING VOLTAGE RANGE | PACKAGE | PACKAGE DRAWING NUMBER ⁽¹⁾ | SPECIFICATION TEMPERATURE RANGE |
|---------------------------------------|--------------------------|-------------------------------|-----------------------------------|---|---------------------------------------|
| OPA241 SERIES | - - | | | | |
| Single OPA241PA OPA241UA | 2.7V to 5V 2.7V to 5V | 2.7V to 36V 2.7V to 36V | 8-Pin DIP SO-8 Surface Mount | 006 182 | -40°C to +85°C -40°C to +85°C |
| Dual OPA2241PA OPA2241UA | 2.7V to 5V 2.7V to 5V | 2.7V to 36V 2.7V to 36V | 8-Pin DIP SO-8 Surface Mount | 006 182 | -40°C to +85°C -40°C to +85°C |
| Quad OPA4241PA OPA4241UA | 2.7V to 5V 2.7V to 5V | 2.7V to 36V 2.7V to 36V | 14-Pin DIP SO-14 Surface Mount | 010 235 | -40°C to +85°C -40°C to +85°C |
| OPA251 SERIES | | | | | |
| Single OPA251PA OPA251UA | ±15V ±15V | 2.7V to 36V 2.7V to 36V | 8-Pin DIP SO-8 Surface Mount | 006 182 | -40°C to +85°C -40°C to +85°C |
| Dual OPA2251PA OPA2251UA | ±15V ±15V | 2.7V to 36V 2.7V to 36V | 8-Pin DIP SO-8 Surface Mount | 006 182 | -40°C to +85°C -40°C to +85°C |
| Quad OPA4251PA OPA4251UA | ±15V ±15V | 2.7V to 36V 2.7V to 36V | 14-Pin DIP SO-14 Surface Mount | 010 235 | -40°C to +85°C -40°C to +85°C |

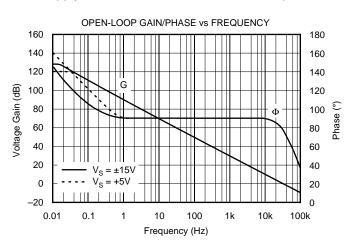
NOTE: (1) For detailed drawing and dimension table, please see end of data sheet, or Appendix C of Burr-Brown IC Data Book.

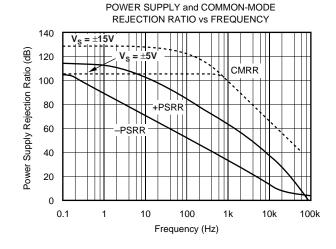


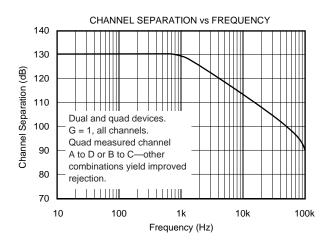
TYPICAL PERFORMANCE CURVES

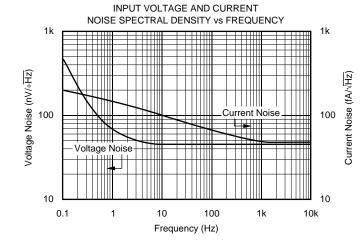
At $T_A = +25^{\circ}C$, and $R_L = 100k\Omega$ connected to $V_S/2$ (ground for $V_S = \pm 15V$), unless otherwise noted.

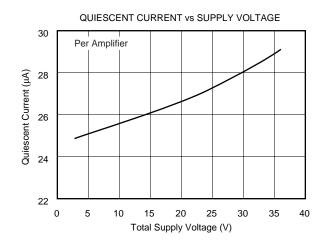
Curves apply to OPA241 and OPA251 unless specified.



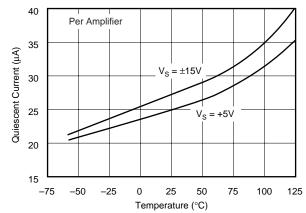








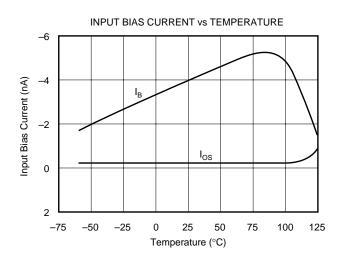
QUIESCENT CURRENT vs TEMPERATURE

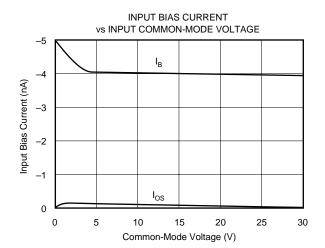




TYPICAL PERFORMANCE CURVES (CONT)

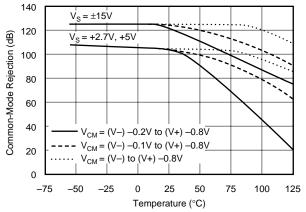
At $T_A = +25^{\circ}$ C, and $R_L = 100 k\Omega$ connected to $V_S/2$ (ground for $V_S = \pm 15$ V), unless otherwise noted. Curves apply to OPA241 and OPA251 unless specified.

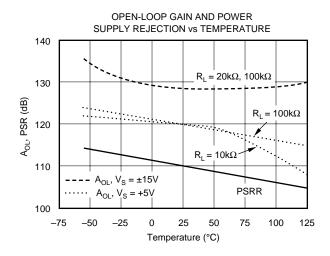


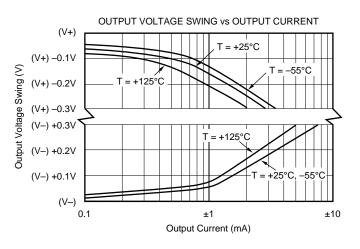


SHORT-CIRCUIT CURRENT vs TEMPERATURE 50 ... 45 40 Short-Circuit Current (mA) I_{sc} 35 ٧s +5 30 25 $V_s = +5V$ 20 Single Versions 15 ····· Dual, Quad Versions $V_s = \pm 15V$ 10 $+I_{SC}$, $V_{S} = +5V$, $\pm 15V$ (all versions) 5 0 25 50 75 100 -75 -50 -25 0 125 Temperature (°C)





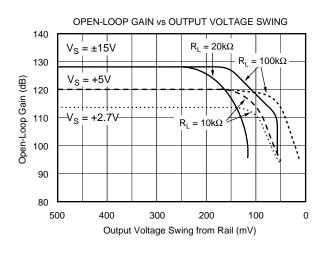






TYPICAL PERFORMANCE CURVES (CONT)

At $T_A = +25^{\circ}$ C, and $R_L = 100 k\Omega$ connected to $V_S/2$ (ground for $V_S = \pm 15$ V), unless otherwise noted. Curves apply to OPA241 and OPA251 unless specified.



OPA241 SERIES OFFSET VOLTAGE

PRODUCTION DISTRIBUTION

Offset Voltage (µV)

 $V_{S} = +5V$

30

25

20

15

10

5

0

-225

Percent of Amplifiers (%)

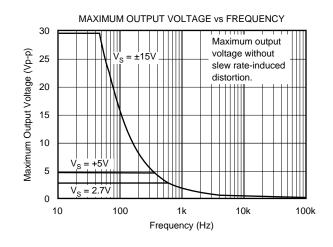
Typical production

and quads included.

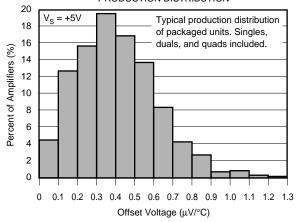
distribution of

packaged units.

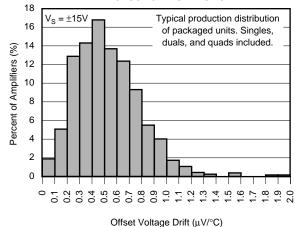
Singles, duals,



OPA241 SERIES OFFSET VOLTAGE DRIFT PRODUCTION DISTRIBUTION



OPA251 SERIES OFFSET VOLTAGE DRIFT PRODUCTION DISTRIBUTION



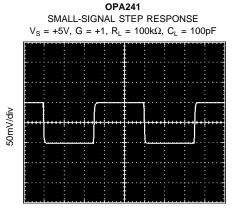
Offset Voltage (µV) **OPA251 SERIES OFFSET VOLTAGE** PRODUCTION DISTRIBUTION 30 $V_{\rm S} = \pm 15V$ Typical production distribution of 25 packaged units. Percent of Amplifiers (%) Singles, duals, 20 and quads included. 15 10 5 0



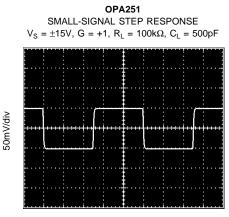
TYPICAL PERFORMANCE CURVES (CONT)

At $T_A = +25^{\circ}$ C, and $R_L = 100$ k Ω connected to $V_S/2$ (ground for $V_S \pm 15$ V), unless otherwise noted. Curves apply to OPA241 and OPA251 unless specified.

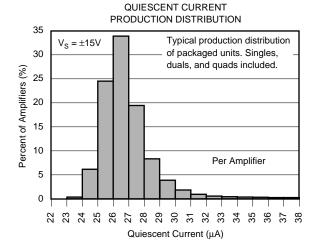
QUIESCENT CURRENT PRODUCT DISTRIBUTION 25 $V_{S} = +5V$ Typical production distribution of packaged units. 20 Percent of Amplifiers (%) Per Amplifier Singles, duals, and quads included. 15 10 5 0 Quiescent Current (µA)

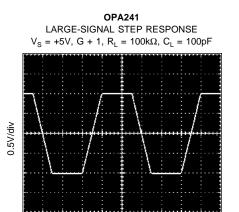


200µs/div

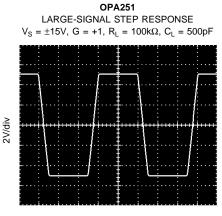


200µs/div





200µs/div



2ms/div



APPLICATIONS INFORMATION

The OPA241 and OPA251 series are unity-gain stable and suitable for a wide range of general purpose applications. Power supply pins should be bypassed with $0.01\mu F$ ceramic capacitors.

OPERATING VOLTAGE

The OPA241 series is laser-trimmed for low offset voltage and drift at low supply voltage ($V_s = +5V$). The OPA251 series is trimmed for ±15V operation. Both products operate over the full voltage range (+2.7V to +36V or ±1.35V to ±18V) with some compromises in offset voltage and drift performance. However, all other parameters have similar performance. Key parameters are guaranteed over the specified temperature range, -40°C to +85°C. Most behavior remains unchanged throughout the full operating voltage range. Parameters which vary significantly with operating voltage or temperature are shown in typical performance curves.

OFFSET VOLTAGE TRIM

As mentioned previously, offset voltage of the OPA241 series is laser-trimmed at \pm 5V. The OPA251 series is trimmed at \pm 15V. Because the initial offset is so low, user adjustment is usually not required. However, the OPA241 and OPA251 (single op amp versions) provide offset voltage trim connections on pins 1 and 5. Offset voltage can be adjusted by connecting a potentiometer as shown in Figure 1. This adjustment should be used only to null the offset of the op amp, not to adjust system offset or offset produced by the signal source. Nulling offset could degrade the offset drift behavior of the op amp. While it is not possible to predict the exact change in drift, the effect is usually small.

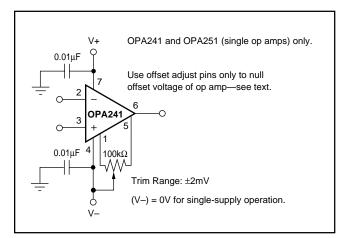


FIGURE 1. OPA241 and OPA251 Offset Voltage Trim Circuit.

CAPACITIVE LOAD AND STABILITY

The OPA241 series and OPA251 series can drive a wide range of capacitive loads. However, all op amps under certain conditions may be unstable. Op amp configuration, gain, and load value are just a few of the factors to consider when determining stability. Figures 2 and 3 show the regions where the OPA241 series and OPA251 series have the potential for instability. As shown, the unity gain configuration with low supplies is the most susceptible to the effects of capacitive load. With $V_S =$ +5V, G = +1, and $I_{OUT} = 0$, operation remains stable with load capacitance up to approximately 200pF. Increasing supply voltage, output current, and/or gain significantly improves capacitive load drive. For example, increasing the supplies to ±15V and gain to 10 allows approximately 2700pF to be driven.

One method of improving capacitive load drive in the unity gain configuration is to insert a resistor inside the feedback loop as shown in Figure 4. This reduces ringing with large capacitive loads while maintaining dc accuracy. For example, with $V_S = \pm 1.35V$ and $R_S = 5k\Omega$, the OPA241 series and OPA251 series perform well with capacitive loads in excess of 1000pF. Without the series resistor, capacitive load drive is typically 200pF for these conditions. However, this method will result in a slight reduction of output voltage swing.

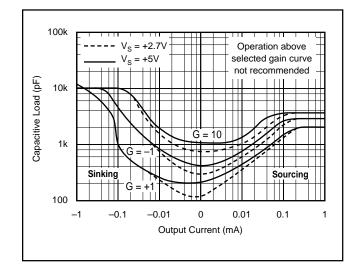


FIGURE 2. Stability—Capacitive Load versus Output Current for Low Supply Voltage.

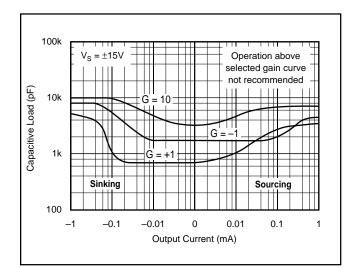


FIGURE 3. Stability—Capacitive Load versus Output Current for ±15V Supplies.



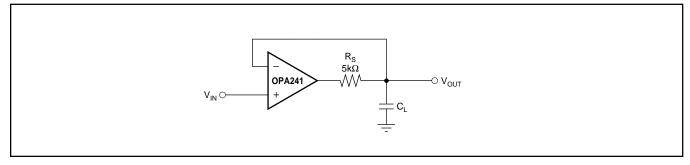


FIGURE 4. Series Resistor in Unity Gain Configuration Improves Capacitive Load Drive.

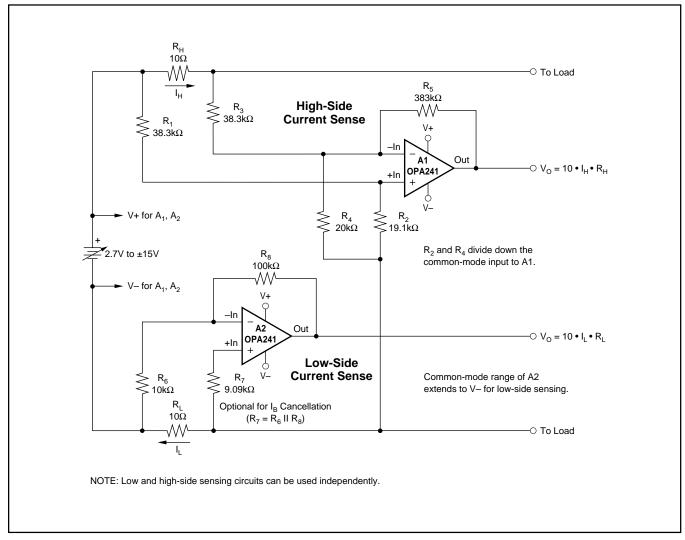


FIGURE 5. Low and High-Side Battery Current Sensing.



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PACKAGING INFORMATION

TEXAS INSTRUMENTS www.ti.com

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Packag Qty | e Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|-----------------|--------------------|------|---------------|---------------------------|------------------|------------------------------|
| OPA2241PA | ACTIVE | PDIP | Р | 8 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type |
| OPA2241PAG4 | ACTIVE | PDIP | Ρ | 8 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type |
| OPA2241UA | ACTIVE | SOIC | D | 8 | 100 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR |
| OPA2241UA/2K5 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR |
| OPA2241UA/2K5G4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR |
| OPA2241UAG4 | ACTIVE | SOIC | D | 8 | 100 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR |
| OPA2251PA | ACTIVE | PDIP | Р | 8 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type |
| OPA2251PAG4 | ACTIVE | PDIP | Р | 8 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type |
| OPA2251UA | ACTIVE | SOIC | D | 8 | 100 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR |
| OPA2251UA/2K5 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR |
| OPA2251UA/2K5G4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR |
| OPA2251UAG4 | ACTIVE | SOIC | D | 8 | 100 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR |
| OPA241PA | ACTIVE | PDIP | Р | 8 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type |
| OPA241PAG4 | ACTIVE | PDIP | Р | 8 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type |
| OPA241UA | ACTIVE | SOIC | D | 8 | 100 | Green (RoHS & no Sb/Br) | Cu NiPdAu | Level-3-260C-168 HR |
| OPA241UA/2K5 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | Cu NiPdAu | Level-3-260C-168 HR |
| OPA241UA/2K5E4 | PREVIEW | SOIC | D | 8 | | TBD | Call TI | Call TI |
| OPA241UA/2K5G4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | Cu NiPdAu | Level-3-260C-168 HR |
| OPA241UAE4 | PREVIEW | SOIC | D | 8 | | TBD | Call TI | Call TI |
| OPA241UAG4 | ACTIVE | SOIC | D | 8 | 100 | Green (RoHS & no Sb/Br) | Cu NiPdAu | Level-3-260C-168 HR |
| OPA251PA | ACTIVE | PDIP | Р | 8 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type |
| OPA251PAG4 | ACTIVE | PDIP | Р | 8 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type |
| OPA251UA | ACTIVE | SOIC | D | 8 | 100 | Green (RoHS & no Sb/Br) | Cu NiPdAu | Level-3-260C-168 HR |
| OPA251UA/2K5 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | Cu NiPdAu | Level-3-260C-168 HR |
| OPA251UA/2K5G4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | Cu NiPdAu | Level-3-260C-168 HR |
| OPA251UAG4 | ACTIVE | SOIC | D | 8 | 100 | Green (RoHS & | Cu NiPdAu | Level-3-260C-168 HR |
| | | | | | | | | |

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Packag Qty | e Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|-----------------|--------------------|------|---------------|----------------------------|------------------|------------------------------|
| | | | | | | no Sb/Br) | | |
| OPA4241PA | ACTIVE | PDIP | Ν | 14 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type |
| OPA4241PAG4 | ACTIVE | PDIP | Ν | 14 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type |
| OPA4241UA | ACTIVE | SOIC | D | 14 | 58 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR |
| OPA4241UA/2K5 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR |
| OPA4241UA/2K5G4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR |
| OPA4241UAG4 | ACTIVE | SOIC | D | 14 | 58 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR |
| OPA4251PA | ACTIVE | PDIP | Ν | 14 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type |
| OPA4251PAG4 | ACTIVE | PDIP | Ν | 14 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | N / A for Pkg Type |
| OPA4251UA | ACTIVE | SOIC | D | 14 | 58 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR |
| OPA4251UA/2K5 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR |
| OPA4251UA/2K5G4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR |
| OPA4251UAG4 | ACTIVE | SOIC | D | 14 | 58 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

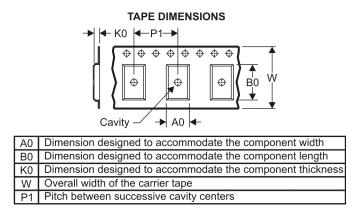
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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



| *All dimensions are nominal | | | | | | | | | | | | |
|-----------------------------|-----------------|--------------------|----|------|--------------------------|--------------------------|---------|---------|---------|------------|-----------|------------------|
| Device | Package Type | Package Drawing | | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
| OPA2241UA/2K5 | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| OPA2251UA/2K5 | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| OPA241UA/2K5 | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| OPA251UA/2K5 | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| OPA4241UA/2K5 | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| OPA4251UA/2K5 | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |



PACKAGE MATERIALS INFORMATION

21-Mar-2008



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---------------|--------------|-----------------|------|------|-------------|------------|-------------|
| OPA2241UA/2K5 | SOIC | D | 8 | 2500 | 346.0 | 346.0 | 29.0 |
| OPA2251UA/2K5 | SOIC | D | 8 | 2500 | 346.0 | 346.0 | 29.0 |
| OPA241UA/2K5 | SOIC | D | 8 | 2500 | 346.0 | 346.0 | 29.0 |
| OPA251UA/2K5 | SOIC | D | 8 | 2500 | 346.0 | 346.0 | 29.0 |
| OPA4241UA/2K5 | SOIC | D | 14 | 2500 | 346.0 | 346.0 | 33.0 |
| OPA4251UA/2K5 | SOIC | D | 14 | 2500 | 346.0 | 346.0 | 33.0 |

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